Specifications

Drawing No.	UKY1C-H1-22521-00[37] 1/12
Issued Date.	Aug.9,2022

TO: Digi-Key

Note: In case of specification change, KYOCERA Part Number also will be changed. Not applicable for military, automotive, implantable medical use, and applications which may cause loss of life or assets.

Product Type	Quartz Crystal	
Series	CX2016SA	
Frequency	Refer to Doc No.UKY1C-H1-22521-00 Page 3/12	
Customer Part Number	-	
Customer Specification Number	-	
KYOCERA Part Number	Refer to Doc No.UKY1C-H1-22521-00 Page 3/12	
Remarks Pb-Free, RoHS Comp	bliant, MSL 1	

Customer Approval

Approval Signature	Approved Date	
	Department	
	Person in charge	

Seller KYOCERA Corporation

Corporate Electronic Components Group Electronic Components Sales Division

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Manufacturer

RF Devices Division Corporate Electronic Components Group Crystal Components Division

Design Department	Quality Assurance	Approved by	Checked by	Checked by	lssued by
KYOCERA Corporation Crystal Components Application Engineering Section1 RF Devices Division Corporate Electronic Components Group	AP Ito 藤	W Muraoka	F. Horie	T. Saito ∰ a	Y. Kik藏hi 地

KYOCERA Corporation

Drawing No.	UKY1C-H1-22521-00[37]	2/12
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Revision History

Rev.No.	Description of revision	Date	Approved by	Checked by	Issued by
00	First Edition	Aug.9,2022	W. Muraoka	F. Horie	Y. Kikuchi

[Part Number list]

Nominal		ESR	Nominal Frequency
Frequency		(Ω)	Code
(MHz)	KYOCERA Part Number		
(*1)		(*2)	(*3)
16.000	CX2016SA16000D0FPLG1	200	16000
20.000	CX2016SA20000D0FPLG1	150	20000
24.000	CX2016SA24000D0FPLG1	150	24000
24.576	CX2016SA24576D0FPLG1	150	24576
25.000	CX2016SA25000D0FPLG1	150	25000
26.000	CX2016SA26000D0FPLG1	60	26000
27.000	CX2016SA27000D0FPLG1	60	27000
30.000	CX2016SA30000D0FPLG1	60	30000
32.000	CX2016SA32000D0FPLG1	60	32000
38.400	CX2016SA38400D0FPLG1	60	38400
40.000	CX2016SA40000D0FPLG1	50	40000
48.000	CX2016SA48000D0FPLG1	50	48000
54.000	CX2016SA54000D0FPLG1	50	54000

1. APPLICATION

This specification sheet is applied to CX2016SA quartz crystal

2. KYOCERA PART NUMBER

Refer to Doc No. UKY1C-H1-22521-00 Page 3/12

3. RATINGS

Items	SYMB.	Rating	Unit	Remarks
Operating Temperature Range	Topr	-40 to +85	°C	
Storage Temperature Range	Tstg	-40 to +125	C°	

4. CHARACTERISTICS ELECTRICAL CHARACTERISTICS

Items		Electrical Specification			Test Condition	Remarks	
	SYMB.	Min	Тур.	Max	Unit		
Mode of Vibration		F	undament	al			
Nominal Frequency	F0		(*1)		MHz		
Nominal Temperature	T _{NOM}		+25		°C		
Load Capacitance	CL		8.0		pF		
Frequency Tolerance	df/F	-10.0		+10.0		+25±3℃	
Frequency Temperature Characteristics	df/F	-20.0		+20.0	PPM	-40 to +85°C	Based on an oscillation frequency at + 25 °C
Frequency Aging Rate		-2.0		+2.0		1 st year	+25±3°C
Equivalent Series Resistance	ESR		(*2)		Ω		
Drive Level	Pd	0.01		200	μW		
Insulation Resistance	IR	500			MΩ	100V(DC)	

*1 *2 Refer to Doc No. UKY1C-H1-22521-00 Page 3/12

5. Measurement Condition

Drive Level

5.1 Frequency measurement

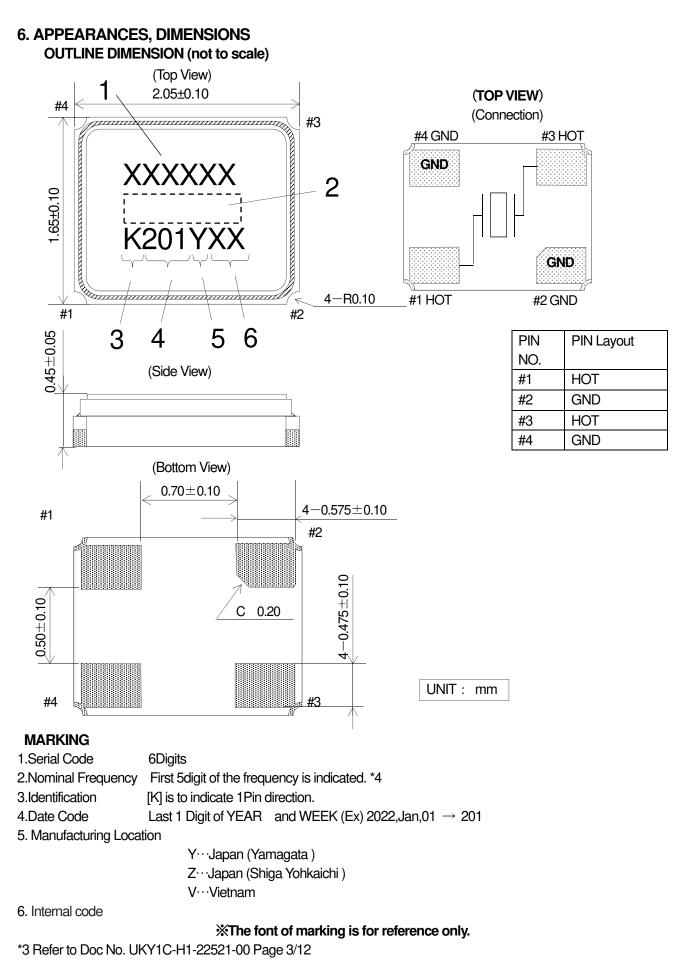
Measuring instrument	: IEC PI-Network Test Fixture
Load Capacitance	: 8.0pF

: 10µW

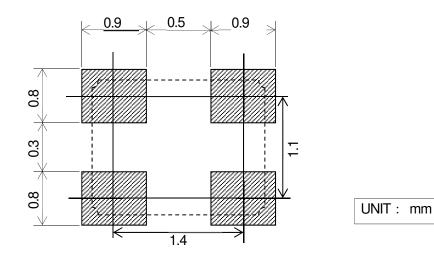
5.2 Equivalent series resistance (ESR) measurement

Measuring instrument : IEC PI-Network Test Fixture Load Capacitance : Series

Drive Level : 10µW

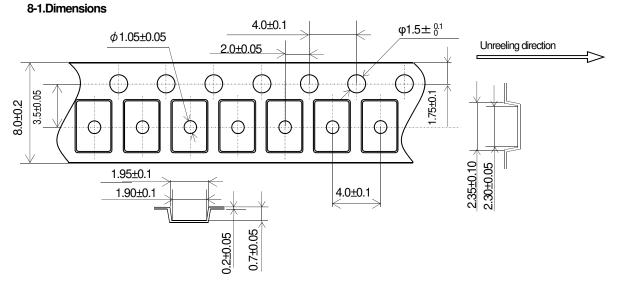


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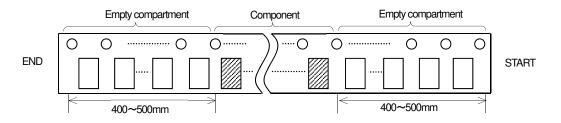


7. RECOMMENDED LAND PATTERN (not to scale)

8. TAPING&REEL



8-2.Leader and trailer tape



8-3.Direction (The direction shall be seen from the top cover tape side)



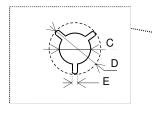
8-4.Specification

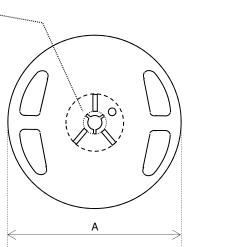
- 1. Material of the carrier tape is either polystyrene or A-PET (ESD).
- 2. Material of the cover tape is polyester (ESD).
- 3. The seal tape shall not cover the sprocket holes and not protrude from the carrier tape.
- 4. Tensile strength of carrier tape: 10N or more.
- 5. The R of the corner of each cavity is 0.2RMAX.
- 6. The alignment between centers of the cavity and sprocket hole shall be 0.05mm or less.
- 7. The orientation shall be checked from the top cover tape side as shown in 8-3.
- 8. Peeling force of cover tape: 0.1 to 1.0N.
- 9. The component will fall out naturally when cover tape is removed and set upside down.

Cover tape 165° -180 Career tape

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8-5.Reel Specification





Б ----В ----

W

t

φ180 Reel (3,000pcs Max)

Symbol	А	В	С	D
Dimension	φ180 +0/-3	φ60 +1/-0	φ13±0.2	φ21±0.8
Symbol	E	W	t	
Dimension	2.0±0.5	9±1	2.0±0.5	

(Unit : mm)

φ330 Reel (15,000pcs Max)

Symbol	А	В	С	D
Dimension	φ330±2.0	φ100±1.0	φ13±0.2	φ21±0.8
Symbol	E	W	t	
Dimension	2.0±0.5	9.5±0.5	2.2±0.1	

(Unit:mm)

9. ENVIRONMENTAL AND MECHANICAL CHARACTERISTICS :

(Reference: AEC-Q200 Rev. D. The solder used by examination is hereafter set to Sn-3Ag-0.5Cu.)

After following test, frequency shall not change more than $\pm 10 \times 10^{-6}$ and CI, $\pm 20\%$ or 5 Ω .

No	Stress	Reference	Additional Requirements
9.1	High Temperature Exposure	MIL-STD-202	1000 hrs. at rated operating temperature (e.g. 85°C
••••	(Storage)	Method 108	part can be stored for 1000 hrs at 85°C. Same applies
	(for 125°C). Unpowered.
			Measurement at 24±4 hours after test conclusion.
9.2	Temperature Cycling	JESD22	1000 cycles (-40°C to 125°C) Note: If 85°C part the 1000
		Method JA-104	cycles will be at that temperature rating.
			Measurement at 24±4 hours after test conclusion.
			30min maximum dwell time at each temperature
			extreme. 1 min. maximum transition time.
9.3	Biased Humidity	MIL-STD-202	1000 hours 85°C/85%RH. Rated VDD applied with 1
		Method 103	MW and inverter in parallel, 2X crystal CL capacitors
			between each crystal leg and GND.
			Measurement at 24±4 hours after test conclusion.
9.4	Operational Life	MIL-STD-202	Note: 1000 hrs @ 125°C. If 85°C part will be tested at
		Method 108	that temperature. Rated VDD applied with 1 MW and
			inverter in parallel, 2X crystal CL capacitors between
			each crystal leg and GND.
			Measurement at 24±4 hours after test conclusion.
9.5	Terminal Strength (Leaded)	MIL-STD- 202	Test leaded device lead integrity only. Conditions: A
		Method 211	(227 g), C (227 g).
9.6	Resistance to Solvents	MIL-STD-202	Note: Also aqueous wash chemical - OKEM clean or
		Method 215	equivalent. Do not use banned solvents.
9.7	Mechanical Shock	MIL-STD-202	Figure 1 of Method 213. Condition C
		Method 213	
9.8	Vibration	MIL-STD-202	5g's for 20 minutes 12 cycles each of 3 orientations.
		Method 204	Note: Use 8"X5" PCB .031" thick with 7 secure points
			on one 8" side and 2 secure points on corners of
			opposite sides. Parts mounted within 2" from any
<u> </u>			secure point. Test from 10-2000 Hz.
9.9	Resistance to	MIL-STD-202	Condition B No pre-heat of samples. Note: Single
	Soldering Heat	Method 210	Wave solder - Procedure 1 with solder within 1.5 mm of
			device body for Leaded. Procedure 1 except 230°C
0.10	Coldor obility		and immerse only to level to cover terminals for SMD.
9.10	Solder ability	J-STD-002	For both Leaded & SMD. Electrical Test not required.
			Magnification 50 X. Conditions: Leaded: Method A @ 235°C, category 3.
			SMD: a) Method B, 4 hrs @ 155°C dry heat @ 235°C
			b) Method B @ 215°C category 3.
			c) Method D category 3 @ 260°C.
9.11	Flammability	UL-94	V-0 or V-1 Acceptable
9.11	Board Flex	AEC Q200-005	60 sec minimum holding time.
9.12	Terminal Strength(SMD)	AEC Q200-005	
J.13			-

10. Soldering condition

1.) Material of solder

Kind \cdots lead free solder paste Melting point \cdots +220±5°C

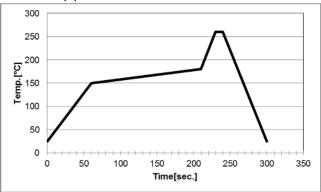
2.) Reflow temp.profile

	Temp [°C]	Time[sec]			
Preheating	+150 to +180	150 (typ.)			
Peak	+260±5	10 (max.)			
Total		300 (max.)			

Frequency shift : ± 2 ppm

- 3.) Hand Soldering +350°C 3 sec MAX
- 4.) Reflow Times 2 times





11. Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.

- When using mounting machine
 Please minimize the shock when using mounting machine to avoid any excess stress to the product.
- (3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 5 times the ESR (Equivalent Series Resistance) of crystal unit.

12. Storage conditions

Please store product in below conditions, and use within 6 months. Temperature +18 to +30°C, and Humidity of 20 to 70 % in the packaging condition.

13. Manufacturing location

Kyocera Corporation Yamagata Higashine Plant / Japan(Yamagata) Kyocera Corporation Shiga Yohkaichi Plant / Japan(Shiga) Kyocera Vietnam Co., LTD. / Vietnam

14. Quality Assurance

To be guaranteed by Kyocera Corporation Yamagata Higashine Plant Quality Assurance Division

15. Quality guarantee

In case when Kyocera Corporation rooted failure occurred within 1 year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1 year of its delivery is waivered.

16. Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.